

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Michael S. Leung,
 et al.
Serial No. 10/666,399
Filed: September 18, 2003
Examiner: Le, Thao X
Art Unit: 2814
Conf. No. 8955
Cust. No. 23935
Docket No. P0298US-7

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed on March 6, 2009, please consider the remarks and arguments presented below and amend the above-identified application as follows:

AMENDMENTS TO THE CLAIMS are shown beginning on page 2 of this paper.

REMARKS AND ARGUMENTS begin on page 12 of this paper.